NanoSpice Pro X

PRIMARIUS

Advanced High Performance FastSPICE Simulator

Introduction

To address increasingly stringent accuracy requirements driven by process node advancements and reduced design margins, NanoSpice Pro X employs an adaptive dual-solver technology that seamlessly integrates the state-of-the-art FastSPICE engine and NanoSpice X analog engine to ensure superior analog accuracy and digital performance for memory circuits, CPU, custom digital, SoC and full chip mixed-signal designs.

With its breakthrough FastSPICE algorithm, intelligent topology recognition & automated partition technology, event-driven architecture with enhanced MT scalability, post-layout circuit topology optimization, significantly improved RC reduction capabilities and straight-forward usability based on circuit types, NanoSpice Pro X delivers superiorer performance and capacity than other simulators.

NanoSpice Pro X supports 3D-IC and multi-technology simulation including back-annotation flow. Empowered by the advanced infrastructure, NanoSpice Pro X optimizes outputs and features such as Circuit Check(CCK), ensuring streamlined efficiency while imposing minimal demands on performance and memory consumption.

In synergy with Primarius NanoSpice product family, NanoSpice Pro X provides an one-stop solution for both memory and SoC design.

Memory Circuit · FPGA

NanoSpice Pro X Faster & More Accurate

Custom Digital · SoC

Scalable
- 2X + parallel SPICE & FastSPICE engines
- Scalable to 32+ threads

Advanced
- 2X+ capacity over NanoSpice Pro
- Circuit topology optimization
- RC reduction

Intelligent
- Usability based on circuit types
- Partition & topology recognition
- Greatly reduced local options

FastSPICE
- Analog accuracy & digital performance
- Foundry validated accuracy

Key Advantages

- **Higher efficiency**
  - 2X to 5X over NanoSpice Pro with better accuracy
  - Event driven with better MT scalability
  - Post layout and RC further optimization
- **Higher accuracy**
  Superior analog accuracy and digital performance with adaptive dual-solver
- **Wider coverage**
  One stop solution from block level to full chip circuit simulation
- **More cost-effective**
  Advanced infrastructure and efficient output system to minimize cost
- **Larger capacity**
  2X+ capacity over NanoSpice Pro with over 2 billion elements
- **Breakthrough algorithm**
  Circuit detection and auto-partitioning empowered by ML/AI

Applications

- Flash/DRAM/SRAM function verification, timing & power dissipation
- SRAM characterization
- Complicated mixed signal (ADC, Serdes, PLL) simulation
- Custom digital (CLK Tree, MCU) full chip simulation
- SoC (Transceiver, Display, CIS, PMIC, etc.) full chip simulation
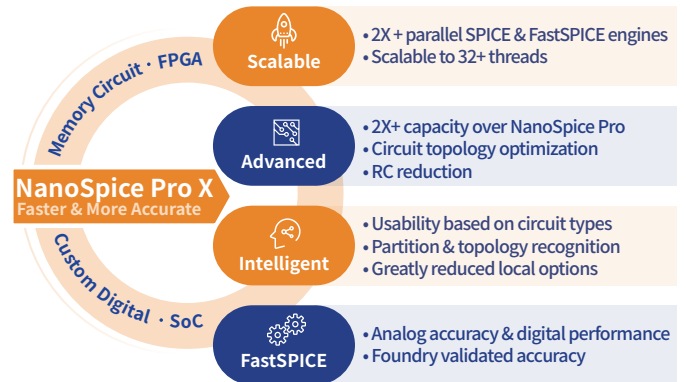
Specifications

- Supports Verilog co-simulation
- Supports 3D-IC and multi-technology Simulation (MTS)
- Supports comprehensive Circuit Check (CCK) and Safe Operation Area (SOA)
- Supports SPEF, DSPF, DPF back-annotation
- Unique transient output format - NWF, reduce 2x+ file size
- Supports standard output formats for data analysis: FSDB, PSFASCII, SPICEASCII, ASCII, etc
- Supports VEC and VCD stimulus files
- Support public cloud platform,hybrid cloud and private cloud
- Supports S-parameter, Transmission line (W-element, T-element), IBIS model
- Supports HSPICE and Spectre netlist formats
- Supports all public domain models, user-defined models
  - MOSFET: BSIM3, BSIM4, BSIM-BULK, BSIM-IMG, BSIM-CMG, BSIM-SOI, LETI-UTSOI, PSP, HiSIM2, HiSIM_HV, EKV3
  - BJT: MAXTRAM, VBIC, HICUM
  - TFT: a-Si TFT, poly-Si TFT
  - Diode: JUNCAP, JUNCAP200, DIODE_CMC
  - Varactor: MOSVAR
  - Resistor: R2_CMC, R3_CMC
  - HEMT: ASM-HEMT
  - JFET/MESFET
- Supports TMI and Custom PMI
- Supports behavioral sources

Application Examples

NanoSpice Pro X Testcase Data benchmark

(Unit: hours)	SRAM Design	SRAM Characterization	DRAM Powerup	DRAM Timing	Flash Full Chip	Flash Module
Ref Simulator	281	263	230	21	189	144
NanoSpice Pro X	50	72	42	5.7	62	28

Speedup ratio: 5.57X (SRAM Design), 3.62X (SRAM Characterization), 5.48X (DRAM Powerup), 3.68X (DRAM Timing), 3.05X (Flash Full Chip), 5.14X (Flash Module)